

# **Description**

The VSM3401A uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications.

#### **General Features**

•  $V_{DS} = -30V, I_{D} = -4.4A$ 

 $R_{DS(ON)}$  <  $85m\Omega$  @  $V_{GS}$ =-2.5V

 $R_{DS(ON)}$  < 65m $\Omega$  @  $V_{GS}$ =-4.5V

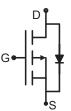
 $R_{DS(ON)}$  <  $52m\Omega$  @  $V_{GS}$ =-10V

- High power and current handing capability
- Lead free product is acquired
- Surface mount package

### **Application**

- PWM applications
- Load switch
- Power management





SOT-23-3

Schematic Diagram

### **Package Marking And Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VSM3401A-S2	VSM3401A	SOT-23-3	Ø180mm	8 mm	3000 units

## Absolute Maximum Ratings (T<sub>A</sub>=25℃unless otherwise noted)

7 moorate maximum reasons go (1 A = 0 o amooration motors)					
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V <sub>DS</sub>	-30	V		
Gate-Source Voltage	Vgs	±12	V		
Drain Current-Continuous	I <sub>D</sub>	-4.4	Α		
Drain Current-Pulsed (Note 1)	I <sub>DM</sub>	-30	Α		
Maximum Power Dissipation	P <sub>D</sub>	1.3	W		
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 150	°C		

#### **Thermal Characteristic**

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	95	°C/W
--------------------------------------------------	----------------	----	------

# Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
Off Characteristics							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =-250µA	-30	-33	-	V	



Shenzhen VSEEI Semiconductor Co., Ltd

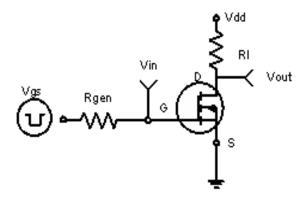
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-30V,V <sub>GS</sub> =0V	-	-	-1	μA	
Gate-Body Leakage Current	I <sub>GSS</sub>	SSS V <sub>GS</sub> =±12V,V <sub>DS</sub> =0V		-	±100	nA	
On Characteristics (Note 3)							
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =-250μA	-0.6	-1	-1.3	V	
		V <sub>GS</sub> =-10V, I <sub>D</sub> =-4.4A	-	42	52	mΩ	
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-4A	-	48	65	mΩ	
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-2A		68	85	mΩ	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =-5V,I <sub>D</sub> =-1A	-	10	-	S	
Dynamic Characteristics (Note4)							
Input Capacitance	C <sub>lss</sub>	\/ - 15\/\/ -0\/	-	950	-	PF	
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> =-15V,V <sub>GS</sub> =0V, F=1.0MHz	-	115	-	PF	
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.0lVlHZ	-	75	-	PF	
Switching Characteristics (Note 4)							
Turn-on Delay Time	t <sub>d(on)</sub>		-	7	-	nS	
Turn-on Rise Time	t <sub>r</sub>	V <sub>DD</sub> =-15V,I <sub>D</sub> =-4A	-	3	-	nS	
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =-10V, $R_{GEN}$ =6 $\Omega$	-	30	-	nS	
Turn-Off Fall Time	t <sub>f</sub>		-	12	-	nS	
Total Gate Charge	Qg		-	9.5	-	nC	
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> =-15V,I <sub>D</sub> =-4A,V <sub>GS</sub> =-4.5V	-	2	-	nC	
Gate-Drain Charge	$Q_{gd}$		-	3	-	nC	
Drain-Source Diode Characteristics							
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =-4.4A	-	-	-1.2	V	

### Notes:

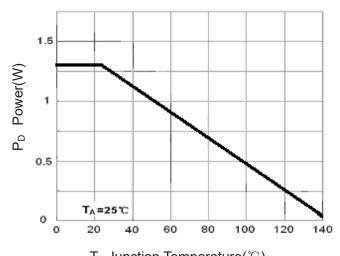
- $\textbf{1.} \ \textbf{Repetitive Rating: Pulse width limited by maximum junction temperature.}$
- **2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- **4.** Guaranteed by design, not subject to production



# **Typical Electrical and Thermal Characteristics**

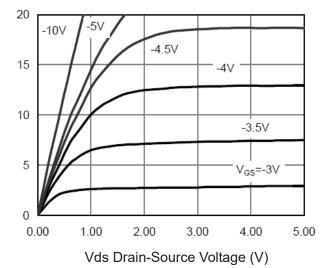


**Figure 1:Switching Test Circuit** 



 $T_J$ -Junction Temperature( $^{\circ}$ C)

**Figure 3 Power Dissipation** 



I<sub>D</sub>- Drain Current (A)

**Figure 5 Output Characteristics** 

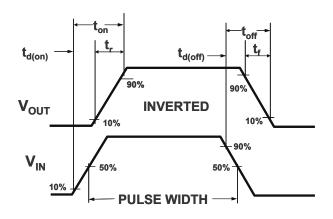
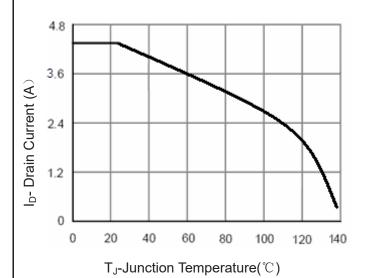


Figure 2:Switching Waveforms



**Figure 4 Drain Current** 

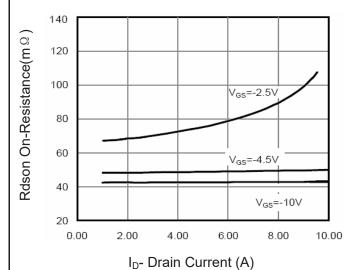
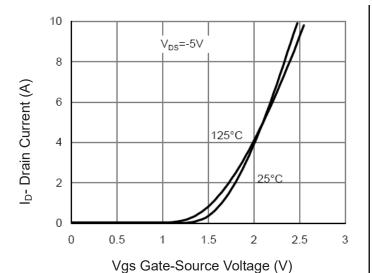
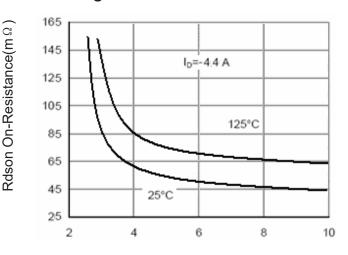


Figure 6 Drain-Source On-Resistance





**Figure 7 Transfer Characteristics** 



Vgs Gate-Source Voltage (V)
Figure 9 Rdson vs Vgs

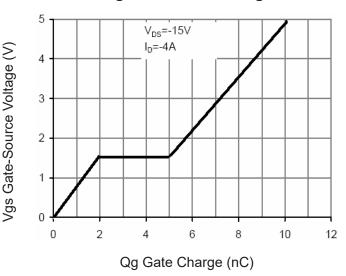
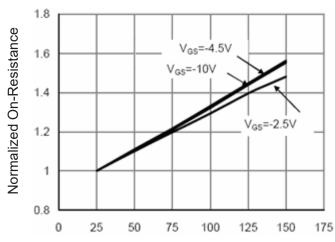
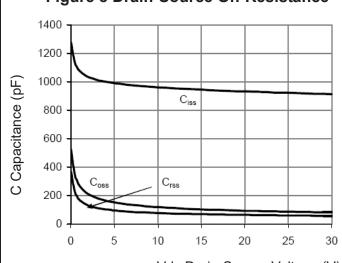


Figure 11 Gate Charge



 $T_J$ -Junction Temperature( ${}^{\circ}\mathbb{C}$ )
Figure 8 Drain-Source On-Resistance



Vds Drain-Source Voltage (V)

Figure 10 Capacitance vs Vds

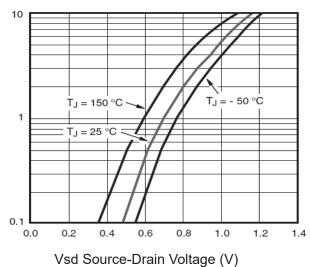


Figure 12 Source- Drain Diode Forward

Is- Reverse Drain Current (A)



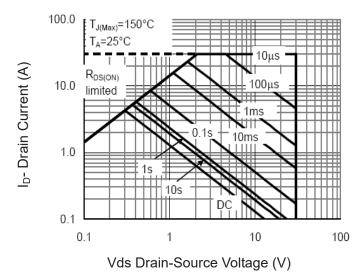
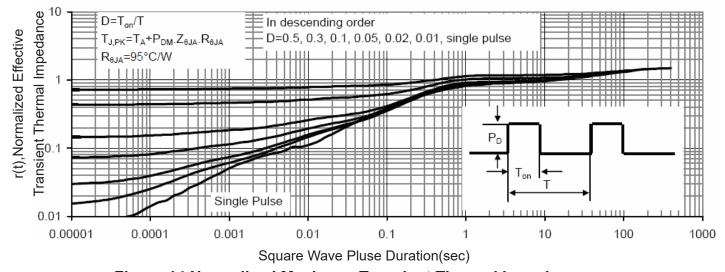


Figure 13 Safe Operation Area



**Figure 14 Normalized Maximum Transient Thermal Impedance**